

Title (en)
ELECTRONIC COMPONENT WITH FLEXIBLE CONTACT STRUCTURES AND METHOD FOR THE PRODUCTION OF SAID COMPONENT

Title (de)
ELEKTRONISCHES BAUELEMENT MIT FLEXIBLEN KONTAKTIERUNGSTELLEN UND VERFAHREN ZUM HERSTELLEN EINES DERARTIGEN BAUELEMENTS

Title (fr)
COMPOSANT ELECTRONIQUE A STRUCTURES DE CONTACT SOUPLES ET PROCEDE DE FABRICATION D'UN TEL COMPOSANT

Publication
EP 1186035 A1 20020313 (DE)

Application
EP 00934894 A 20000411

Priority
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• DE 19927750 A 19990617

Abstract (en)
[origin: WO0079589A1] Disclosed is an electronic component with an electronic circuit and electronic contacts which are disposed at least on the first surface (2) of the electronic component to enable contacting of said electronic circuit. At least one flexible elevation (3) made of an insulating material is arranged on the first surface (2) and at least one electrical contact (1) is arranged on the at least one flexible elevation (3). A line path (8) is disposed on the surface of or inside the flexible elevation (3) between the at least one electrical contact (1) and the electronic circuit.

IPC 1-7
H01L 23/485

IPC 8 full level
H01L 23/12 (2006.01); **H01L 21/60** (2006.01); **H01L 23/485** (2006.01)

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C-Set (source: EP US)
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Citation (search report)
See references of WO 0079589A1

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